## Mirror Mezz - High Speed, Low Height, BGA Mezzanine Connector



#### **Features**







1 Molex "Mirror Mezz" Licensed Second Source

- 2 High Speed Transmission (56+Gbps NRZ / 112+Gbps PAM4)
- 3 OAM Specified Connector
- 4 High Pin Count, High Density: 688pos. (172DPs/in<sup>2</sup>)
- **5 Hermaphroditic Connector**
- 6 Stub-less 2-point Contact Design
- 7 Protective Housing that Encapsulates the Contact Tips **Prevents Warping During Mating**

#### **Contact Design**

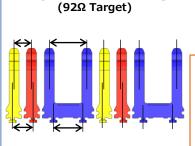
### **Used in OAM\* (OCP Accelerator Module)**

#### **Specifications**

# 2-point Contact

**Stub-less Design** 

- Superior SI Performance ·2-point Contact for
- **Enhanced Reliability**
- ·Wiping Amount: 1.5mm Max.



**Impedance Matching** 

Pitch differs from contact portion and mounted portion for impedance optimization.



(2.5mm + 2.5mm)688pos. 172 Differential Pairs

	Top Stiffener Board
	OAM* Board
t	Booot Booot Basaq

Rated Current	1.2A
Rated Voltage	30V AC/DC
Operating Temperature	-55 to +105℃
Contact Resistance*	30mΩ Max.
Withstanding Voltage	500V DC for 1min.
Insulation Resistance	1000MΩ (500V DC)
Mating Durability	100 times
Impedance	92Ω

\*Includes conductor resistance.

- -Cross mates with Molex's Mirror Mezz.
- -No. of Pos. : 688pos.



\*OAM = OCP (Open Computer Project) Accelerator Module